

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims

Claim 1 (previously presented): A system for managing electronics manufacturing data comprising:

- a processor;
- a data storage device operably connected to the processor, the data storage device storing manufacturing standardization data and a plurality of electronic manufacturing data sets, each of the plurality of electronic manufacturing data sets corresponding to a local manufacturing process; and
- a difference editor executable on the processor to display differences between at least one of the electronic manufacturing data sets and the manufacturing standardization data.

Claim 2 (original): The system of claim 1 wherein the data storage device includes a server for providing the manufacturing standardization data.

Claim 3 (original): The system as recited in claim 2 wherein the data storage device further includes a control system for providing a first of the plurality of electronic manufacturing data sets, the processor being located at the control system.

Claim 4 (previously presented): The system as recited in claim 1 wherein the data storage device includes a central server for providing the manufacturing standardization data, a first control system for providing a first of the plurality of electronic manufacturing data sets, and a second control system for providing a second of the plurality of electronic manufacturing data sets.

Claim 5-10 (canceled)

Claim 11 (previously presented): A method for managing of electronics manufacturing data, in which the data comprises non-local data and local data, comprising the steps of:

 permitting non-local electronics manufacturing data to be modified by a first set of persons;

 permitting local electronics manufacturing data to be modified by a second set of persons;

 displaying differences between the local electronics manufacturing data and the non-local electronics manufacturing data so as to permit a comparison between local electronics manufacturing data and non-local electronics manufacturing data wherein the first and second sets of persons are not identical.

Claim 12 (cancelled)

Claim 13 (previously presented): The method as recited in claim 11 wherein the displaying step includes displaying a graphical representation of an electronic component.

Claim 14 (previously presented): The method as recited in claim 11 wherein the displaying step includes highlighting the differences.

Claim 15 (previously presented): The method as recited in claim 11 wherein the displaying step includes displaying lead information of an electronic component.

Claim 16 (original): The method as recited in claim 11 wherein the local electronics manufacturing data includes information regarding a length of electronic component leads.

Claim 17 (original): The method as recited in claim 11 wherein the non-local electronics manufacturing data includes a specification for a length of electronic component leads.

Claim 18 (currently amended): A manufacturing system comprising:

 a first assembly line having a first controller, the first controller containing a first set of manufacturing data related to a product manufactured by the first assembly line;

a server providing a ~~second set of manufacturing data~~ standardization specification for the product to the first controller; and
a display displaying differences between the first set of manufacturing data and the ~~second set of manufacturing data~~ standardization specification.

Claim 19 (canceled)

Claim 20 (original): The manufacturing system as recited in claim 18 wherein the product is a printed circuit board.

Claim 21 (original): The manufacturing system as recited in claim 18 wherein the display includes a first window for the first set of manufacturing data and a second window for the second set of manufacturing data.

Claim 22 (original): The manufacturing system as recited in claim 18 wherein the first set of data includes information relating to a plurality of electric components.

Claim 23 (previously presented): A printed circuit board assembly line comprising:
at least one placement machine for placing components on a printed circuit board;
a controller connected to the placement machine; and
a display connected to the controller for comparing a first set of information regarding actual characteristics for the components and a second set of information regarding desired characteristics for the components.

Claim 24 (original): The printed circuit board assembly line as recited in claim 23 further comprising a server connected to the display, the server providing the second set of information.

Claim 25 (original): The printed circuit board assembly line as recited in claim 23 further comprising a quality control device for examining the components on the printed circuit board, the quality control device being connected to the controller and being controlled as a function of the first set of information.

Claim 26 (original): A method for displaying differences between a first set of electronics manufacturing data and a second set of electronics manufacturing data comprising the steps of:

displaying the first set of electronics manufacturing data on a section of a display, the first set of electronics manufacturing data including a list of components being used in an assembly line;

displaying the second set of electronics manufacturing data on an other section of the display, the second set of electronics manufacturing data including another list of component desired to be manufactured on the assembly line; and

displaying differences between the first and second set of electronics manufacturing data.

Claim 27 (original): The method as recited in claim 26 wherein the differences are displayed through highlighting.

Claim 28 (original): The method as recited in claim 26 wherein the assembly line is a printed circuit board assembly line.

Claim 29 (currently amended): A method for manufacturing a printed circuit board comprising the steps of:

conveying a printed circuit board;

placing at least one component on the printed circuit board using a placement machine as a function of a first set of electronics manufacturing data;

transferring the first set of electronics manufacturing data to a display;

transferring a set of electronics manufacturing standardization data to the display, and

comparing the first set of electronics manufacturing data with ~~a second set of the~~ electronics manufacturing standardization data on the display.

Claim 30 (original): A printed circuit board manufactured according to the method of claim 29.